

PC/ LED/ IC 自動化設備
解決方案

AllRing Tech 萬潤科技簡介

Presented by Allring

About Us

Establish

May 24. 1996

Chairman

Larry Lu

Capital

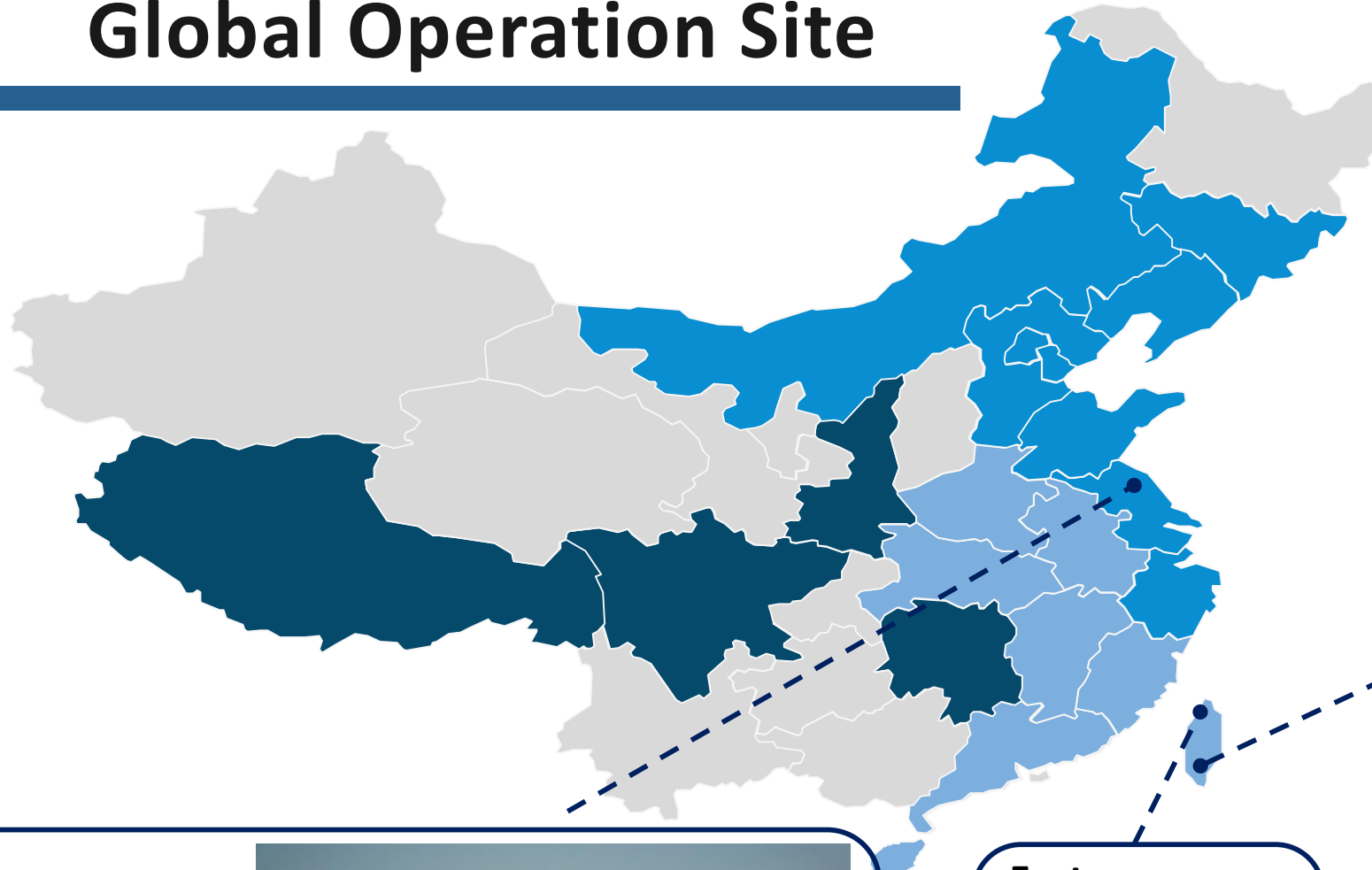
833 Million

Business

Automation equipment supplier for
Semiconductor test & package, Passive Component
manufacturing industries



Global Operation Site



Subsidiary

◆ Kunshan

Jiangsu

Factory Area:
20,000 m²



Factory

◆ Hsinchu

◆ Taichung

Headquarters

Kaohsiung/Taiwan

Factory Area: 27,000 m²

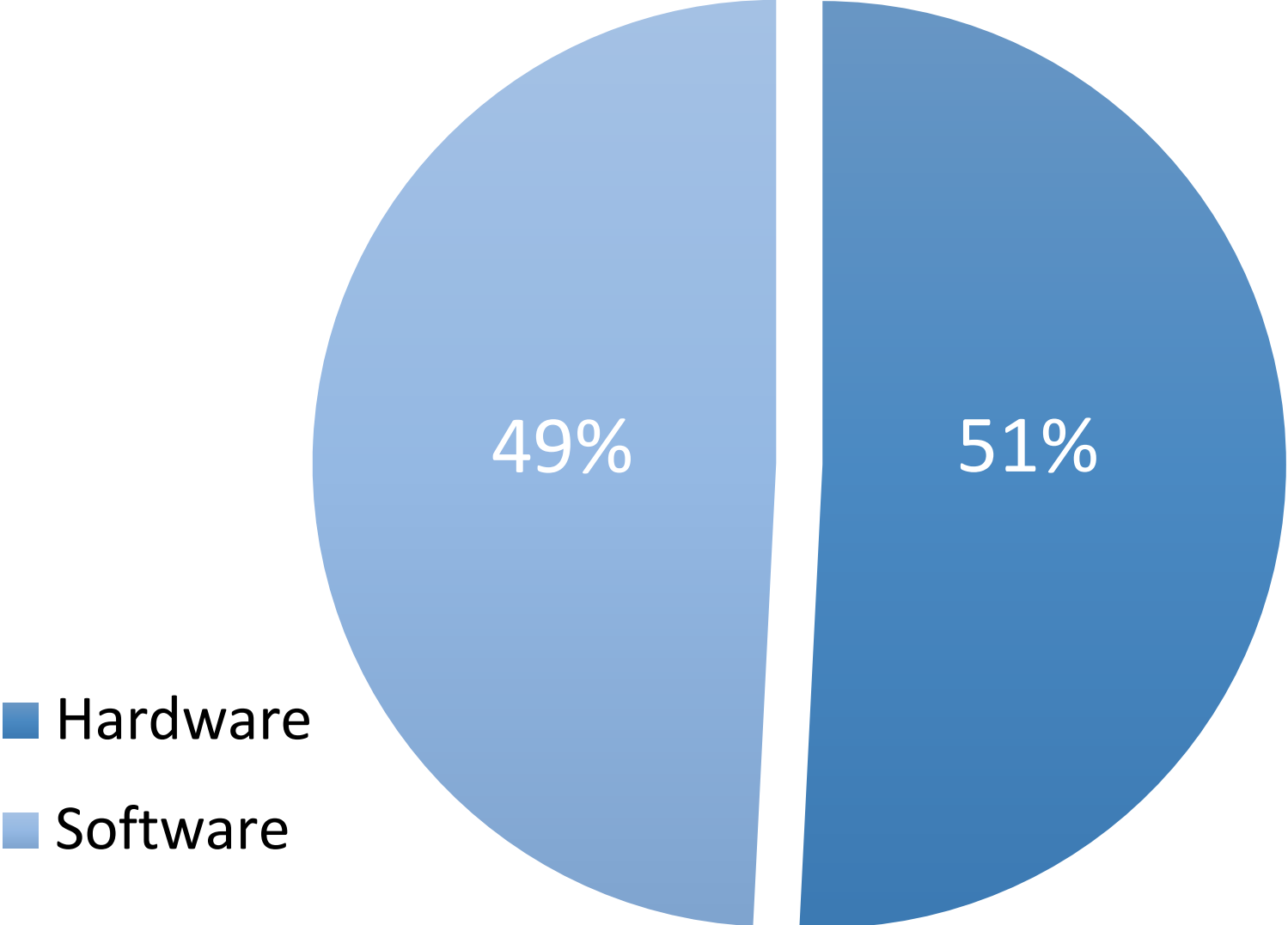


Human Resources R&D

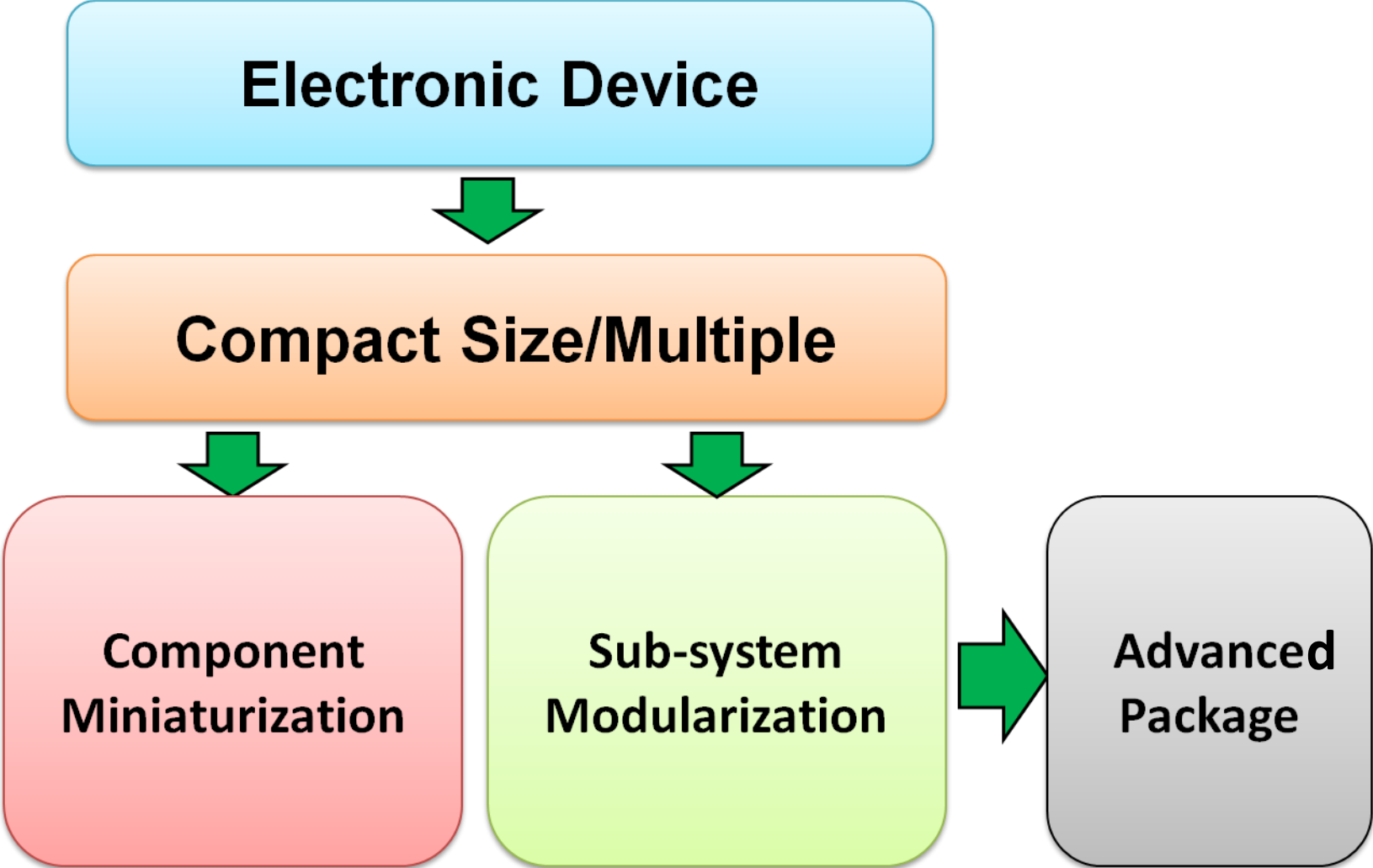
60%

R&D

Human Resources R&D



Industry Overview



Advanced Package

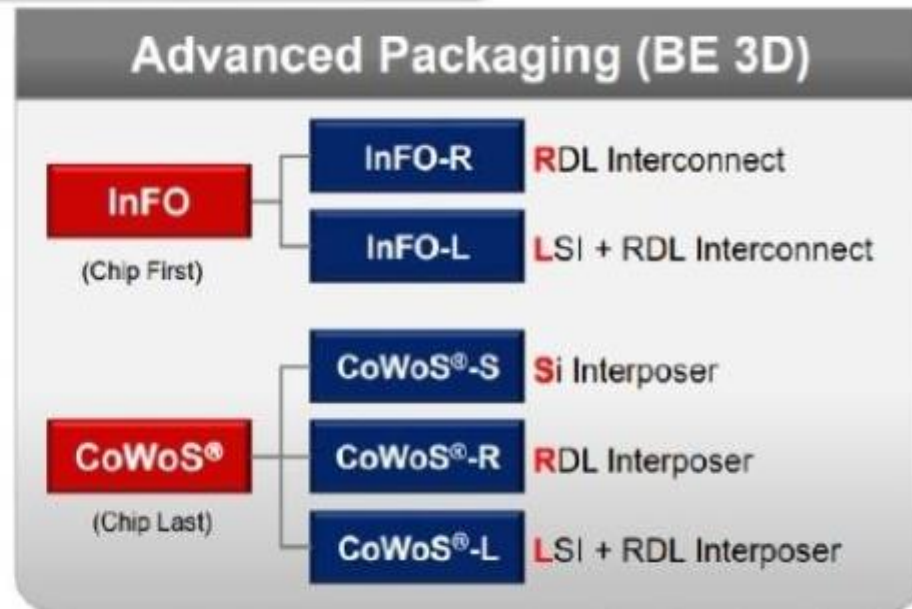
Packaging Type		Manufacturer		Application
SiP (System in Package)		OSAT	ASE	Smart phone IoT Mobile
			USI	
		Module house	GIS	
			Luxshare	
		Component	AAC	
			AMS	
3D Package	InFO,CoWoS	Foundry	TSMC	Smart Phone IoT Mobile
	SoIC		TSMC	
Flip chip	2D/2.5D	OSAT	ASE	Smart Phone IoT Mobile
			Spil	
			Amkor	
			Chipbond	
			Powertech	

TSMC's 3D Fabric

TSMC 3DFabric™



SoIC: System on Integrated Chips



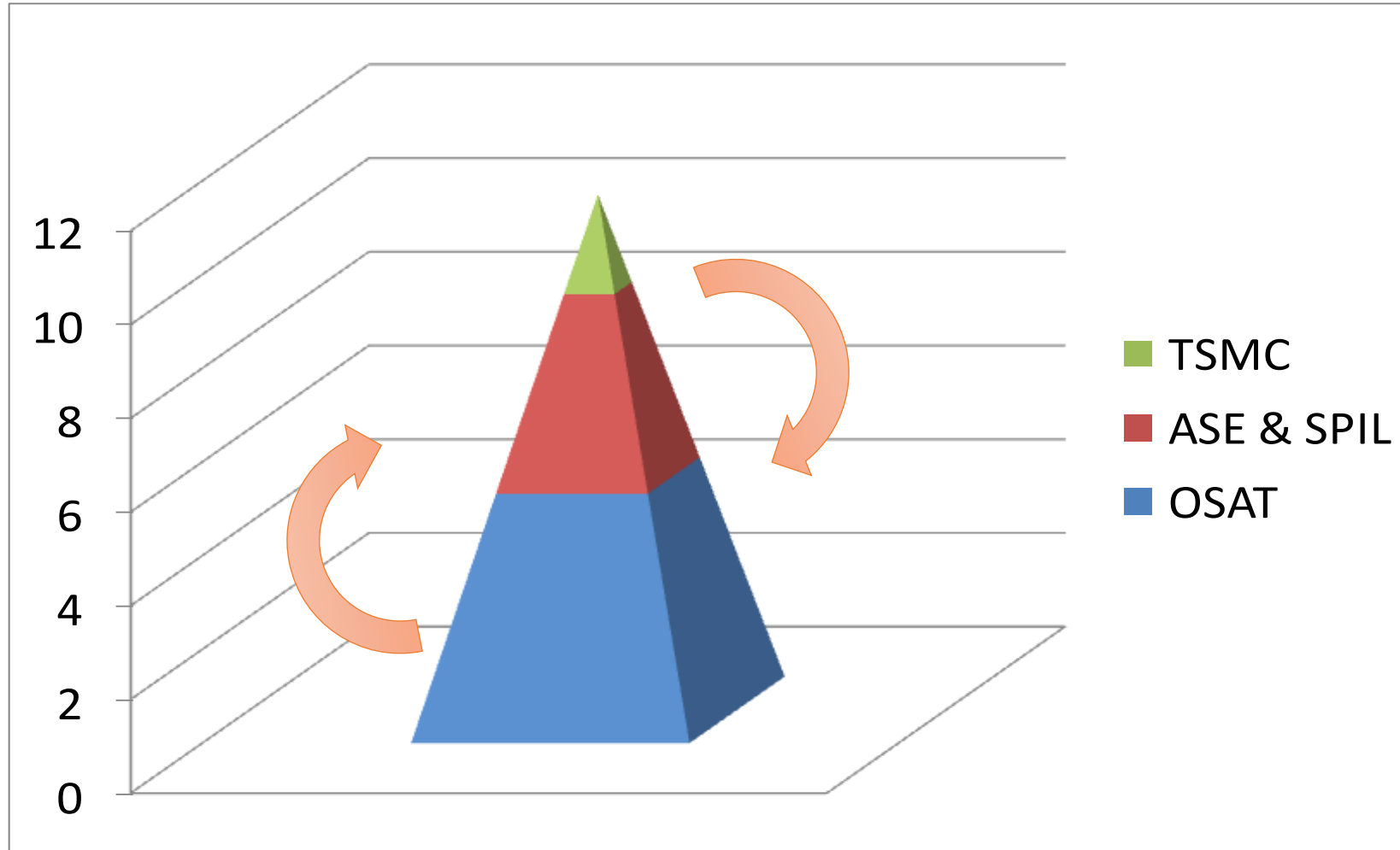
InFO: Integrated Fan-Out
CoWoS: Chip on Wafer on Substrate
RDL: Redistribution Layer
LSI: Local Si Interconnect

resource from:TSMC

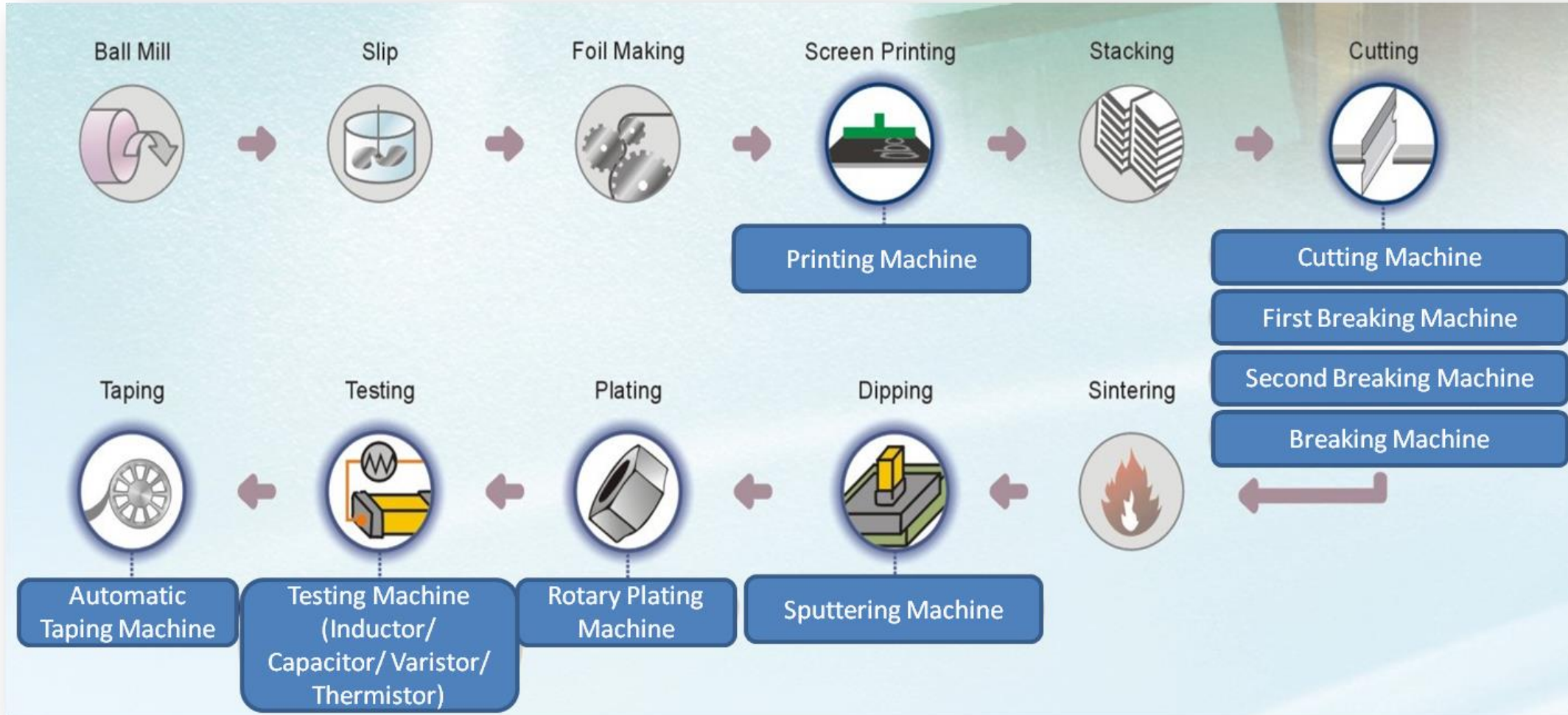
CoWoS Process Flow



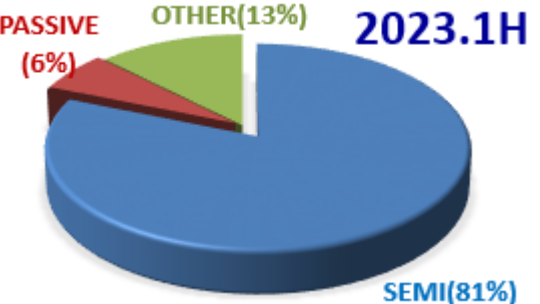
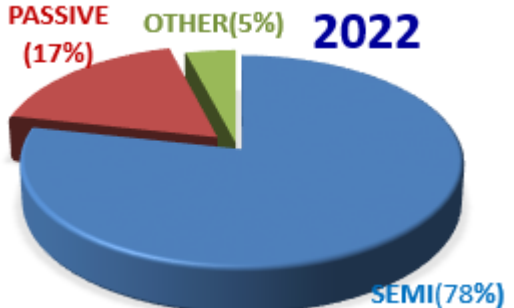
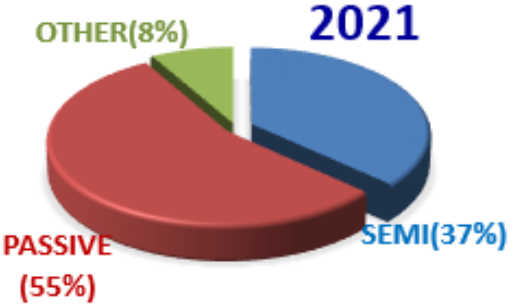
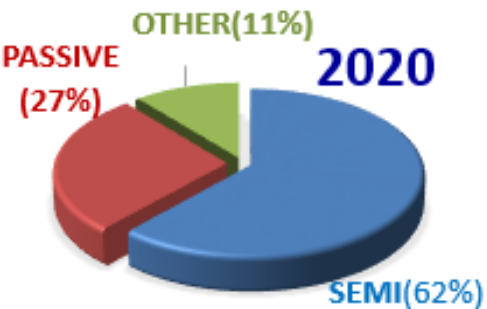
Target



Passive Component Production Process



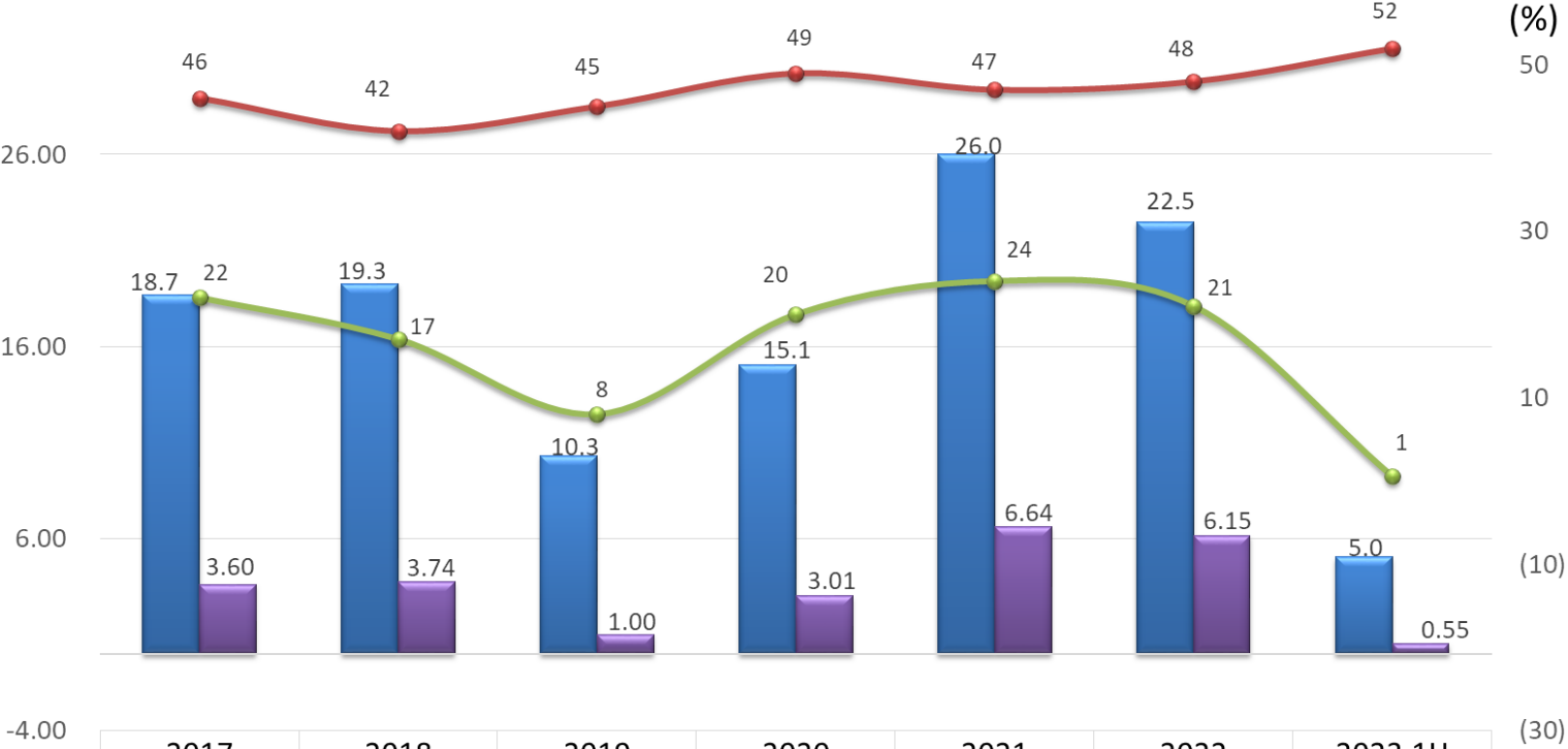
Financial Information



NT\$100M
2023.1H

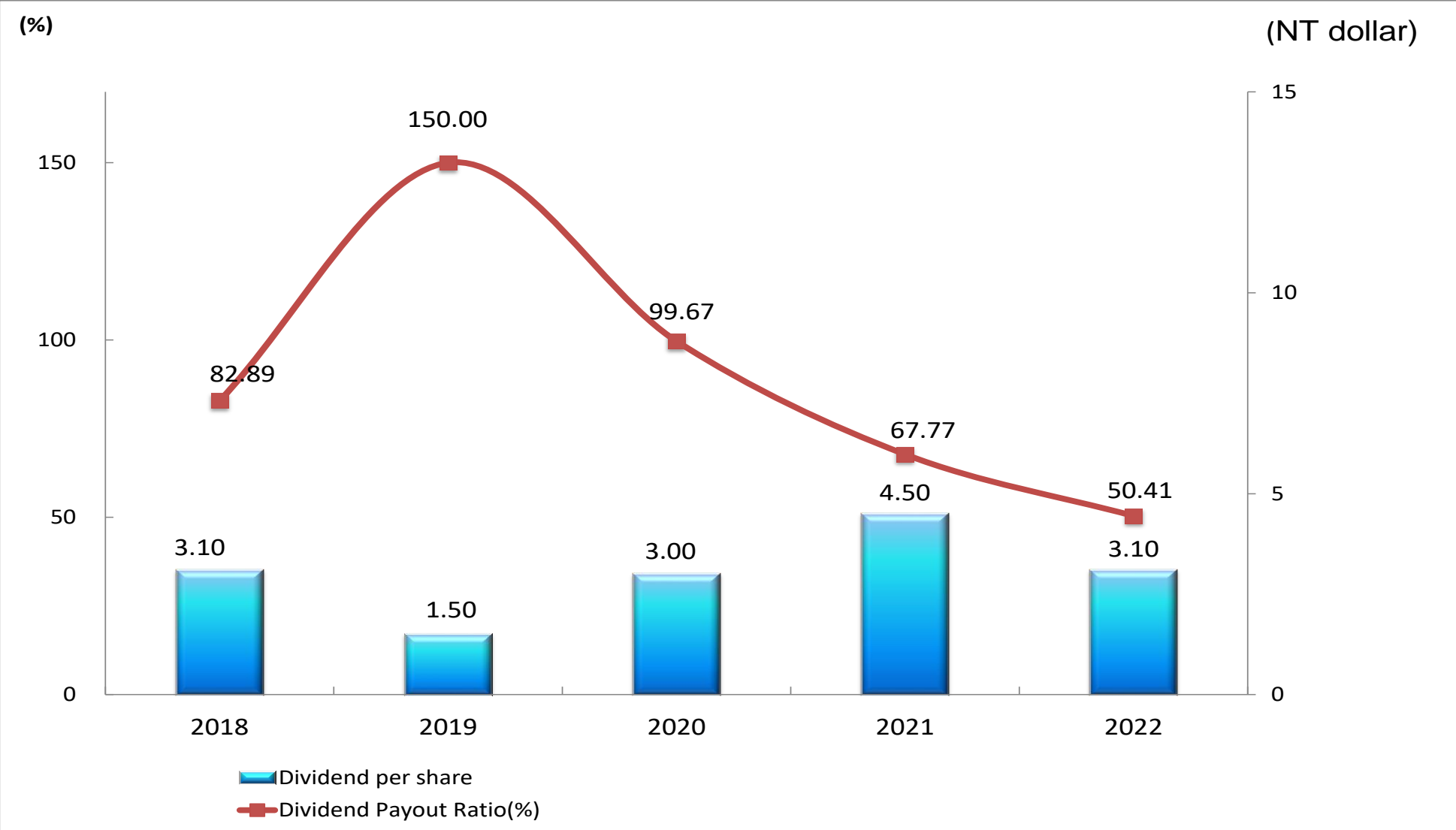
	2020		2021		2022		2023.1H	
SEMI	9.28	62%	9.60	37%	17.63	78%	4.09	81%
PASSIVE	4.14	27%	14.29	55%	3.93	17%	0.32	6%
OTHER	1.64	11%	2.15	8%	0.92	5%	0.63	13%
TOTAL	15.06	100%	26.04	100%	22.48	100%	5.04	100%

Financial Highlights



	2017	2018	2019	2020	2021	2022	2023.1H
Sales(NT\$100mn)	18.7	19.3	10.3	15.1	26.0	22.5	5.0
EPS(NT\$)	3.60	3.74	1.00	3.01	6.64	6.15	0.55
GM(%)	46	42	45	49	47	48	52
OPM(%)	22	17	8	20	24	21	1

Financial Highlights





Thank you!